



Final Product Change Notification

201512004F01

Issue Date: 13-Jun-2016

Effective Date: 25-Sep-2016

Dear

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

Assembly site transfer for the 20pin DIP packages of the 8 Bit Microcontroller Product Line from assembly site APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to Amkor Philippines.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage

Assembly Site Transfer for MCU 20pin DIP Packages (APB Thailand to Amkor Philippines)

Details of this Change

These products are End of Life (EOL) and this PCN is only to meet the final End of Life shipment commitments.

Transfer remaining production of 20pin DIP packages from APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to subcontractor Amkor Philippines.

NXP will transfer all remaining production of 20pin DIP packages from in-house assembly APB (Bangkok) to the subcontractor Amkor Philippines.

There will be no changes to the test location. Wafer testing will be performed at APK and final test will be performed at APB.

Package assembly will be transferred from APB to Amkor with the following BOM changes:

1. Leadframe will be changed from NXP DIP20 PPF Leadframe to Amkor DIP20 CuFe2P leadframe with Ag spot plating. This is the standard Amkor leadframe and is being changed due to compatibility with Amkor tooling.
2. Die-attach will be changed from Henkel 71-1D to Henkel 8361J, which is standard die-attach material at Amkor Philippines.
3. Wire size will change from 20um to 25um.
4. Mold compound will change from EME-6210SR-L to Sumitomo G600, which is standard material at Amkor Philippines.

5. Lead finish will change from PPF to Matte Tin.
6. Tube will change from NXP DIP20 tube to Amkor Philippines DIP20 tube.

Please refer to the attached PDF file for all the Package Outline Drawing (POD) changes. DIP20 POD changes from SOT146-1 to SOT146-5.

The POD changes include changes to the total package height, standoff height, package thickness, outer leadwidth, package length, tip to tip distance and package width.

The two critical POD differences are:

- 1) Package length 'D' is changing from min-max of 1.045in - 1.060in to a min-max of 1.025in to 1.035in.
- 2) Length from edge of package to pin 1, the 'Z' dimension on POD is not measured at Amkor.

Why do we implement this Change

The 20pin DIP packages have been identified as End Of Life (EOL) products.

In order to support last time buy shipments, NXP has decided to transfer the DIP assembly to NXP's subcontractor Amkor to have sufficient load to maintain these DIP assembly lines.

Identification of Affected Products

Top side marking

Only line 3, second letter, on assembly centre code will be changed from 'n' to 'u'

n - ABP Assembly, G - Green

u - Amkor Assembly, D - Dark Green

(Old-TnGYWW, New-TuDYYWW)

Product Availability

Sample Information

Samples are available from 15-Jul-2016

Production

Planned first shipment 30-Jul-2016

Impact

no impact to the product's functionality anticipated.

No impact on function, quality, reliability and manufacturability is anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 13-Jul-2016.

For information on shipping and logistics related issues please contact BL Operations Manager Brian Alkins at brian.alkis@nxp.com

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

P87LPC764BN,112

P87LPC762BN,112

P89LPC922FN,112

P87LPC762FN,112

P87LPC768FN,112

P87LPC767BN,112